Spec. No.:
 RMPC-K-HTS-0001 /4

 Date:
 2022.8.18

## Data sheet

Title: FIXED THICK FILM CHIP RESISTORS;

RECTANGULAR TYPE AND Pb<100ppm

Style: RMPC04,06,10,16,20,32,35

# RoHS COMPLIANCE ITEM Halogen and Antimony Free

Note: •Stock conditions

Temperature:  $+5^{\circ}$ C ~  $+35^{\circ}$ C Relative humidity: 25% ~ 75%

The period of guarantee: Within 2 year from shipment by the company.

Solderability shall be satisfied.

- Product specification contained in this data sheet are subject to change at any time without notice
- •If you have any questions or a Purchasing Specification for any quality agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya

Drawing No: RMPC-K-HTS-0001 /4

Style

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND Pb<100ppm

RMPC04,06,10,16,20,32,35 Page: 1/14

#### 1. Scope

1.1 This specification covers the detail requirements for fixed thick film chip resistors; rectangular type, style of RMPC04, 06, 10, 16, 20, 32, 35.

#### 1.2 Applicable documents

JIS C 5201–1: 2011, JIS C 5201–8: 2014, JIS C 5201–8–1: 2014 IEC60115–1: 2008, IEC60115–8: 2009, IEC60115–8–1: 2014 EIAJ RC–2134C–2010

#### 2. Classification

Type designation shall be the following form.

(Example)

1)	RMPC	16		123	J	_TP_
	1	2	3	4	5	6
	Style	<u>.</u>				
2)	RMPC	16		JP		TP
	1	2		4		6
	Style					

- 1 Fixed thick film chip resistors; rectangular type & Pb<100ppm
- 2 Dimension
- 3 Temperature coefficient of resistance

–(Dash)	Standard

#### 4 Rated resistance

123	E24 Series, 3 digit,	Ex. 123-> 12kΩ,
1000	E96 Series, 4 digit,	Ex. 1000->100Ω
		1022-> 10.2kΩ
JP	Chip jumper	

#### 5 Tolerance on rated resistance

F	±1%
J	±5%

#### 6 Packaging form

9 101111		
В	Bulk (loose package) Press pocket taping	
PA		
TH	Dan antanina	
TP	Paper taping	
TE Embossed taping		

Drawing No: RMPC-K-HTS-0001

FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND Pb<100ppm RMPC04,06,10,16,20,32,35 Page: 2/14

#### 3. Rating

The ratings shall be in accordance with Table–1.

#### 3.1 Resistor

Table-1(1)

Г	Rated	Temperat	Table-1( ure coefficient of	ĺ		
Style	dissipation		sistance	Rated resistance	Preferred number	Tolerance on
Otyle	(W)		10-6 / °C)	range ( $\Omega$ )	series for resistors	rated resistance
	()		±200	100~1M	F04.00	<b>-</b> (. (-()
			+600~0	10~97.6	E24, 96	F(±1%)
RMPC04	0.03	Standard	±200	100~1M		
			+600~0	10~9.1	E24	J(±5%)
			+800~-100	1~9.1		,
			±200	100~10M		
			+600~0	10~97.6	E24, 96	F(±1%)
DMDCOC	0.05	Ctorodoval	+800~-100	1~9.76		,
RMPC06	0.05	Standard	±200	100~10M		
			+600~0	10~91	E24	J(±5%)
			+800~-100	1~9.1		, ,
			±200	100~10M		
			+500~-200	10~97.6	E24, 96	F(±1%)
RMPC10	0.063	Standard	+800~-100	1~9.76		
RIVIPCIO	0.063	Staridard	±200	100~10M		
			+500~-200	10~91	E24	J(±5%)
			+800~-100	1~9.1		
			±200	100~10M		
			+500~-200	10~97.6	E24, 96	F(±1%)
RMPC16	0.1	Standard	+800~-100	1~9.76		
HIVIECTO	0.1	Standard	±200	100~10M	E24	J(±5%)
			+500~-200	10~91		
			+800~-100	1~9.1		
			±200	100~10M		
			+500~-200	10~97.6	E24, 96	F(±1%)
RMPC20	0.125	Standard	+800~-100	1~9.76		
111011 020	0.125	Staridard	±200	100~10M		
			+500~-200	10~91	E24	J(±5%)
			+800~-100	1~9.1		
			±200	100~10M		
			+500~-200	10~97.6	E24, 96	F(±1%)
RMPC32	0.25	Standard	+800~-100	1~9.76		
I IIVII OOZ	0.20	Januaru	±200	100~10M		
			+500~-200	10~91	E24	J(±5%)
			+800~-100	1~9.1		
			±200	100~10M		
			+500~-200	10~97.6	E24, 96	F(±1%)
RMPC35	0.33	Standard	+800~-100	1~9.76		
I IIVII COO	0.55	Siandard	±200	100~10M		
			+500~-200	10~91	E24	J(±5%)
			+800~-100	1~9.1		

RMPC04,06,10,16,20,32,35 Page: 3/14

Style	Limiting element voltage (V)	Insulation voltage (V)	Category temperature range (°C)	
RMPC04	15	50		
RMPC06	25	50		
RMPC10	50	100		
RMPC16	30	100	<i>–</i> 55∼+125	
RMPC20	150			
RMPC32	200	500		
RMPC35	200			

#### 3.2 Chip Jumper

Table-1(2)

Style	Chip jumper symbol	Resistance value of chip jumper	Rated current of chip jumper(A)
RMPC04			0.5
RMPC06			1
RMPC10			1
RMPC16	JP	50mΩmax.	2
RMPC20			2
RMPC32			2
RMPC35			2

#### 3.3 Climatic category

55/125/56 Lower category temperature  $-55\,^{\circ}\text{C}$  Upper category temperature  $+125\,^{\circ}\text{C}$ 

Duration of the damp heat, steady state test 56days

#### 3.4 Stability class

5% Limits for change of resistance:

 $\begin{array}{ll} -\text{for long-term tests} & \pm (5\% + 0.1 \Omega) & \text{Chip jumper: } 50 \text{ m}\Omega \text{ max.} \\ -\text{for short-term tests} & \pm (1\% + 0.05 \Omega) & \text{Chip jumper: } 50 \text{ m}\Omega \text{ max.} \\ \end{array}$ 

#### 3.5 Derating

The derated values of dissipation (or current rating in case of chip jumper) at temperature in excess of 70 °C shall be as indicated by the following curve.

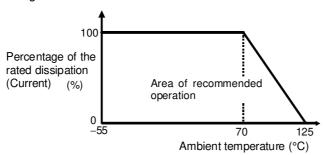


Figure-1 Derating curve

Drawing No: RMPC-K-HTS-0001 /4

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND Pb<100ppm

RMPC04,06,10,16,20,32,35 Page: 4/14

#### 3.6 Rated voltage

d. c. or a. c. r. m. s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

$$E = \sqrt{\begin{array}{c} E : Rated \ voltage \ (V) \\ P : Rated \ dissipation \ (W) \\ R : Rated \ resistance \ (\Omega) \end{array}}$$

Limiting element voltage can only be applied to resistors when the resistance value is equal to or higher than the critical resistance value.

At high value of resistance, the rated voltage may not be applicable.

#### 4. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	Packaging form		Standard packaging quantity / units	Application
В	Bulk (loose package)	Bulk (loose package)		RMPC04,06,10,16,20,32,35
PA	Press pocket taping   9mm width 2mm nitches		20,000 pcs.	RMPC04
FA	(paper taping)	8mm width, 2mm pitches	15,000 pcs.	RMPC06
TH	Paper taping	8mm width, 2mm pitches	10,000 pcs.	RMPC10
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	RMPC16,20,32
TE	Embossed taping	8mm width, 4mm pitches	4,000 pcs.	RMPC35

#### 5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-3.

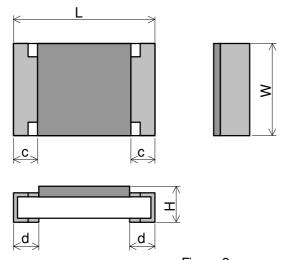


Figure-2

Table\_3 Unit: mm

		iabi	0 0	O	
Style	L	W	Н	С	d
RMPC04	0.4±0.02	0.2±0.02	0.13±0.02	0.08±0.03	0.1±0.03
RMPC06	0.6±0.03	0.3±0.03	0.23±0.03	0.1±0.05	0.15±0.05
RMPC10	1.0±0.05	0.5±0.05	0.35±0.05	0.2±0.1	$0.25_{-0.10}^{+0.05}$
RMPC16	1.6±0.1	0.8 <sup>+0.15</sup>	0.45±0.10	0.3±0.1	0.3±0.1
RMPC20	2.0±0.1	1.25±0.10	0.55±0.10	0.4±0.2	0.4±0.2
RMPC32	3.1±0.1	1.6±0.15	0.55±0.10	0.5±0.25	0.5±0.25
RMPC35	3.1±0.15	2.5±0.15	0.55±0.15	0.5±0.25	0.5±0.25

Drawing No: RMPC-K-HTS-0001

FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND Pb<100ppm

RMPC04,06,10,16,20,32,35 Page: 5/14

#### 5.2 Net weight (Reference)

Style	Net weight(mg)
RMPC04	0.035
RMPC06	0.16
RMPC10	0.6
RMPC16	2
RMPC20	5
RMPC32	9
RMPC35	16

#### 6. Marking

The Rated resistance of RMPC04,06,10 should not be marked.

#### 6.1 RMPC16,20,32,35

The nominal resistance shall be marked in 3 digits or 4 digits and marked on over coat side.

• RMPC20,32,35: E24 series: 3 digits, E96 series: 4 digits

In case of the resistance value that E96 overlaps with E24, It is marked by either.

• The Rated resistance of RMPC16 should not be marked in 4 digits.

Marking example	Contents	Application
123	$12\times10^3 \ [\Omega] \rightarrow 12 \ [k\Omega]$	RMPC16,20,32,35
2R2	2.2 [Ω]	Less than $10\Omega$ of RMPC16,20,32,35
5623	$562\times10^3 [\Omega] \rightarrow 562[k\Omega]$	RMPC20,32,35
12R7	12.7 [Ω]	RMPC20,32,.35

#### 6.2 Marking example of Jumper Chip

Marking example	Contents	Application	
0	JP	RMPC16,20,32	
000	JF	RMPC35	

Drawing No: RMPC-K-HTS-0001

Page:

6/14

FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND Pb<100ppm RMPC04,06,10,16,20,32,35

#### 7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201–1: 2011.

7.2 The performance shall be satisfied in Table-4.

Table 4(1)

No.	Test items	Condition of test (JIS C 5201-1)	Performance requirements	
1	Visual examination	Sub-clause 4.4.1 Checked by visual examination.	As in 4.4.1 The marking shall be legible, as	
2	Dimension	Sub-clause 4.4.2	checked by visual examination.  As specified in Table–3 of this specification.	
	Resistance	Sub-clause 4.5	As in 4.5.2  The resistance value sha correspond with the rated resistance taking into account the specified tolerance.  Chip jumper: 50mΩ max.	
3	Voltage proof	Sub-clause 4.7 Method: 4.6.1.4(See Figure-3) Test voltage: Alternating voltage with a peak value of 1.42 times the insulation voltage.  Duration: 60 s ± 5 s Insulation resistance Test voltage: Insulation voltage Duration: 1 min.	No breakdown or flash over $R \geq 1 \; G \; \Omega$	
4	Solderability	Sub-clause 4.17 Without ageing Flux: The resistors shall be immersed in a non-activated soldering flux for 2s. Bath temperature: 235 °C ±5 °C Immersion time: 2 s ± 0.5 s	As in 4.17.4.5 The terminations shall be covered with a smooth and bright solder coating.	

Drawing No: RMPC-K-HTS-0001 /4

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND Pb<100ppm

RMPC04,06,10,16,20,32,35 Page: 7/14

Table-4(2)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
5	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
	Overload	Sub-clause 4.13	
	(in the mounted state)	The applied voltage shall be 2.5 times the	
		rated voltage or twice the limiting element	
		voltage, whichever is the less severe.	
		Duration: 2 s	
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
			Chip jumper: $50m\Omega$ max.
	Solvent resistance of the	Sub-clause 4.30	Legible marking
	marking	Solvent: 2-propanol	
		Solvent temperature: 23 °C ± 5 °C	
		Method 1	
		Rubbing material: cotton wool	
		Without recovery	
6	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
	Bound strength of the end face	Sub-clause 4.33	
plating		Bent value: 3 mm	
		Resistance	$\Delta R \leq \pm (1\% + 0.05\Omega)$
Final managements			Chip jumper: 50mΩ max.
	Final measurements	Sub-clause 4.33.6	No visible damage
		Visual examination	
7	Resistance to soldering heat	Sub-clause 4.18	
		Solder temperature: 260 °C ± 5 °C	
		Immersion time: 10 s ± 0.5 s	A - 1 - 4 d 0 0 A
		Visual examination	As in 4.18.3.4
		Davistanas	No sign of damage such as cracks.
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	Component solvent resistance	Sub-clause 4.29	Chip jumper: $50 \text{m}\Omega$ max.
	Component solvent resistance		
		Solvent: 2-propanol Solvent temperature: 23 °C ± 5 °C	
		Method 2	
		Recovery: 48 h	
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
			Chip jumper: $50m\Omega$ max.
			Onip Jumper, Jumsz max.

Drawing No: RMPC-K-HTS-0001

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND Pb<100ppm

RMPC04,06,10,16,20,32,35 Page: 8/14

#### Table-4(3)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
8	Mounting Adhesion Rapid change temperature	Sub-clause 4.31 Substrate material: Epoxide woven glass Sub-clause 4.32 Force: 3N (RMPC04: 2N, RMPC06: 3N) Duration: 10 s ± 1 s Visual examination Sub-clause 4.19 Lower category temperature: -55 °C Upper category temperature: +125 °C	No visible damage
		Duration of exposure at each temperature: 30 min.  Number of cycles: 5 cycles.  Visual examination Resistance	No visible damage $\Delta \ R \leq \pm (1\% + 0.05\Omega)$ Chip jumper: $50 \mathrm{m}\Omega$ max.
9	Climatic sequence  —Dry heat	Sub-clause 4.23 Sub-clause 4.23.2 Test temperature: +125 °C Duration: 16 h	
	-Damp heat, cycle (12+12hour cycle) First cycle	Sub-clause 4.23.3 Test method: 2 Test temperature: 55 °C [Severity(2)]	
	-Cold	Sub-clause 4.23.4 Test temperature –55 °C Duration: 2h	
	-Damp heat, cycle (12+12hour cycle) Remaining cycle	Sub-clause 4.23.6 Test method: 2 Test temperature: 55 °C [Severity (2)] Number of cycles: 5 cycles	
	–D.C. load	Sub-clause 4.23.7  The applied voltage shall be the rated voltage or the limiting element voltage whichever is the smaller.  Duration: 1 min.  Visual examination Resistance	No visible damage $\Delta R \le \pm (5\%+0.1\Omega)$ Chip jumper: $50m\Omega$ max.

Drawing No: RMPC-K-HTS-0001

FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND Pb<100ppm

RMPC04,06,10,16,20,32,35 Page: 9/14

#### Table-4(4)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
10			i enormance requirements
10	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
	Endurance at 70 °C	Sub-clause 4.25.1	
	Lindard 100 dt 70 °C	Ambient temperature: 70 °C ± 2 °C	
		Duration: 1000 h	
		The voltage shall be applied in cycles of 1.5 h	
		on and 0.5 h.	
		The applied voltage shall be the rated voltage	
		or the limiting element voltage whichever is the	
		smaller.	
		Examination at 48 h , 500 h and	
	1000 h:		
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (5\% + 0.1\Omega)$
			Chip jumper: 50mΩ max.
11	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure–3	
	Variation of resistance with	Culs alaura 4.0	As in Table–1
	temperature	Sub-clause 4.8 -55 °C / +20 °C	AS III IADIC—I
	tomporataro		
12	Mounting	+20 °C / +125°C Sub-clause 4.31	
12	i woo iii ig	Substrate material: Epoxide woven glass	
		Cabbilate material. Eponide Woverrylass	
	Damp heat, steady state	Sub-clause 4.24	
		Ambient temperature: 40 °C ± 2 °C	
		Relative humidity: $93^{+2}_{-3}$ %	
		a) 1st group: without voltage applied.	
		b) 2nd group: The d. c. voltage shall be applied	
	continuously.		
		The voltage shall be accordance with	
		Sub-clause 4.24.2.1 b). without polarizing	
		voltage	
		[4.24.2.1, c)]	No visible damage
		Visual examination	Legible marking
		Rosistanco	$\Delta R \le \pm (5\% + 0.1\Omega)$
		Resistance	Chip jumper: $50m\Omega$ max.
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table–3
	Mounting	Sub-clause 4.31	
	Endurance at upper category temperature	Substrate material: Epoxide woven glass	
		TSub-clause 4.25.3	
		Ambient temperature:125 °C $\pm$ 2 °C	
		Duration: 1000 h	
		Examination at 48 h, 500 h and	
		1000 h:	No visible demage
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (5\% + 0.1\Omega)$
			Chip jumper: $50m\Omega$ max.

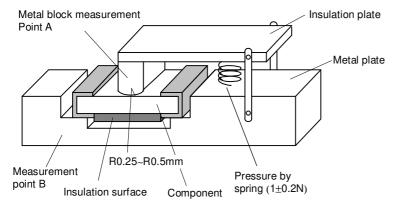
Drawing No: RMPC-K-HTS-0001 /4

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND Pb<100ppm

RMPC04,06,10,16,20,32,35 Page: 10/14

#### - RMPC10,16,20,32,35

#### · RMPC04,06



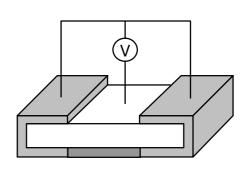


Figure-3

#### 8. Taping

- 8.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010
- 8.2 Taping dimensions
- 8.2.1 Press pocket taping (Paper taping, 8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-4 and Table-5.

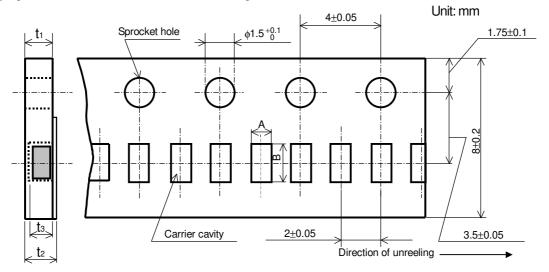


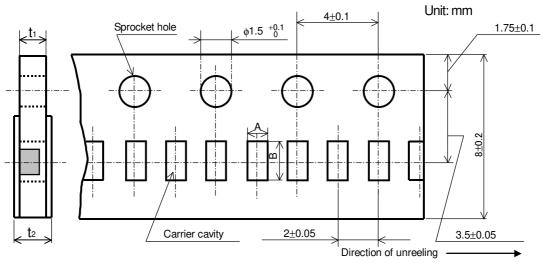
Figure-4

Iable-5				Unit: mm	
Style	Α	В	t 1	t <sub>2</sub>	t <sub>3</sub>
RMPC04	0.24±0.03	0.45±0.03	0.31±0.03	0.36±0.03	0.15±0.02
RMPC06	0.37±0.05	0.67±0.05	0.42±0.03	0.45±0.05	0.27±0.02

RMPC04,06,10,16,20,32,35 Page: 11/14

#### 8.2.2 Paper taping (8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-5 and Table-6.



Figure–5 Table–6 Unit: mm Style A B  $t_1$   $t_2$  RMPC10  $0.65^{+0.05}_{-0.10}$   $1.15^{+0.05}_{-0.10}$   $0.4\pm0.05$  0.5max.

#### 8.2.3 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-6 and Table-7.

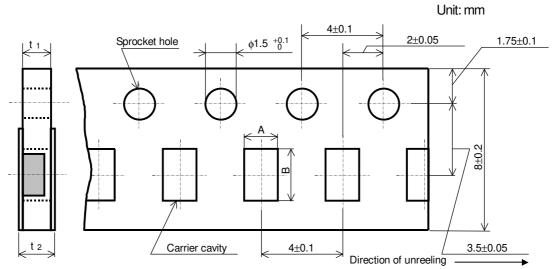
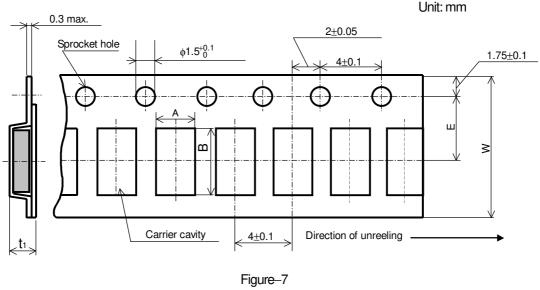


Figure-6 Table-7 Unit: mm A В Style tı RMPC16 1.15±0.15 1.9±0.2  $0.6\pm0.1$ 0.8max. RMPC20 1.65±0.15 2.5±0.2 0.8±0.1 1.0max. RMPC32 2.00±0.15 3.6±0.2

RMPC04,06,10,16,20,32,35 Page: 12/14

#### 8.2.4 Embossed taping dimensions shall be in accordance with Figure-7 and Table-8.



Figure—7

Table—8

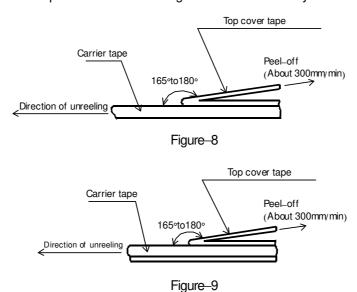
Unit: mm

Style A B W E t 1

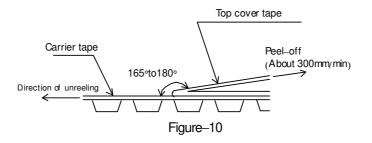
RMPC35 2.85±0.20 3.5±0.2 8.0±0.2 3.5±0.05 1.0±0.2

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following RMPC04,06: Figure–8, RMPC10,16,20,32: Figure–9, RMPC35: Figure–10.
- 6). When the tape is bent with the minimum radius for 25 mm the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.

  The maximum number of missing components shall be one or 0.1%, whichever is greater.
- 8). The resistors shall be faced to upward at the over coating side in the carrier cavity.

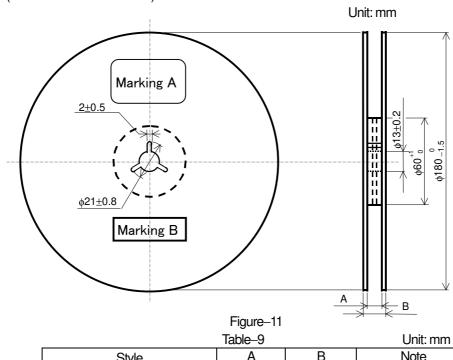


RMPC04,06,10,16,20,32,35 Page: 13/14



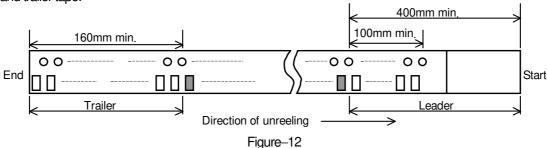
#### 8.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–11 and Table–9. Plastic reel (Based on EIAJ ET–7200C)



Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

#### 8.4 Leader and trailer tape.



Drawing No: RMPC-K-HTS-0001

FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND Pb<100ppm

RMPC04,06,10,16,20,32,35 Page: 14/14

#### 9. Marking on package

The label of a minimum package shall be legibly marked with follows.

#### 9.1 Marking A

- (1) Classification
  - (Style, Temperature coefficient of resistance, Rated resistance, Tolerance on rated resistance, Packaging form)
- (2) Quantity (3) Lot number (4) Manufacturer's name or trade mark (5) Others
- 9.2 Marking B (KAMAYA Control label)

### 单击下面可查看定价,库存,交付和生命周期等信息

### >>Kamaya(釜屋电机)